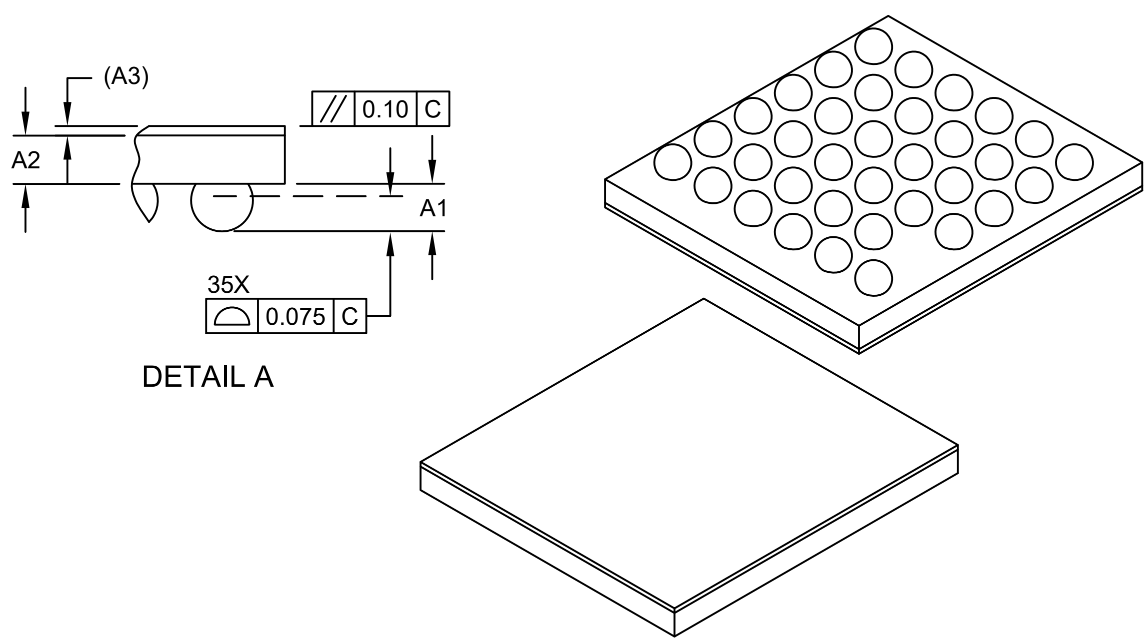
35-Ball Wafer Level Chip Scale Package (FQB) - 2.821x2.529 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		35	
Pitch	e		0.40 BSC	
Overall Height	A	-	-	0.483
Bump Height	A1	0.17	0.20	0.23
Die Thickness	A2	0.178	0.203	0.228
Backside Coating	A3		0.04 REF	
Overall Length	D		2.529 BSC	
Overall Bump Pitch	D1		2.00 BSC	
Overall Width	E		2.821 BSC	
Overall Bump Pitch	E1		2.00 BSC	
Terminal Width	b	0.23	0.26	0.29

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.